AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A support for a lithographic printing plate obtained by performing graining treatment including electrochemical graining treatment on an aluminum plate, wherein said aluminum plate contains Fe of 0.05 to 0.29 wt%, Si of 0.03 to 0.15 wt%, Cu of 0.025 to 0.050 wt%, Ti of 0.05 wt% or less and Mg of less than 0.05 wt% and the remaining portion thereof is composed of aluminum and unavoidable impurities, said aluminum plate having an aluminum purity of 99.28% or more,

wherein said aluminum plate is such that the plate thickness t (mm) thereof is 0.10 to 0.50 (mm) and the relation between said plate thickness t (mm) and the tensile strength TS (MPa) of said aluminum plate in a rolling direction satisfies the following equation [I]

Equation [1]:

 $-98.6 \times t + 170 \le TS \text{ (MPa)} \le -98.6 \times t + 200.$

2. (canceled).

3. (previously presented): The support for a lithographic printing plate according to claim 1, wherein said aluminum plate is such that for intermetallic compounds existent on the surface thereof, an intermetallic compound with a circle equivalent diameter of 1 μ m or more is of 6,000 pieces/mm² or less and the rate of an intermetallic compound with a circle equivalent diameter of 1 to 10 μ m is 85% or higher.

4. (canceled).

5. (original): The support for a lithographic printing plate according to claim 1, wherein said aluminum plate is such that for crystal grains located in the area up to 50 μ m deep from the surface thereof, the width in a direction perpendicular to a plate rolling direction is an average of 80 μ m or less and a maximum of 150 μ m or less, and the length of the plate rolling direction is an average of 400 μ m or less and a maximum of 500 μ m or less.

6. (canceled).

7. (original): The support for a lithographic printing plate according to claim 3, wherein said aluminum plate is such that for crystal grains located in the area up to 50 μ m deep from the surface thereof, the width in a direction perpendicular to a plate rolling direction is an average of 80 μ m or less and a maximum of 150 μ m or less, and the length of the plate rolling direction is an average of 400 μ m or less and a maximum of 500 μ m or less.

- **8. (original):** The support for a lithographic printing plate according to claim 1, wherein Si atom adhesion quantity onto the surface of said aluminum plate is 0.1 to 30 mg/m².
 - 9. (canceled).
- **10. (original):** The support for a lithographic printing plate according to claim 3, wherein Si atom adhesion quantity onto the surface of said aluminum plate is 0.1 to 30 mg/m².
- **11. (original):** The support for a lithographic printing plate according to claim 5, wherein Si atom adhesion quantity onto the surface of said aluminum plate is 0.1 to 30 mg/m².
- **12. (original):** A presensitized plate provided with an image recording layer on the support for a lithographic printing plate according to claim 1.
 - 13. (canceled).
- **14. (original):** A presensitized plate provided with an image recording layer on the support for a lithographic printing plate according to claim 3.

- **15. (original):** A presensitized plate provided with an image recording layer on the support for a lithographic printing plate according to claim 5.
- **16. (original):** The presensitized plate according to claim 12, which is a presensitized plate for a laser printing plate.
- **17. (original):** A method of treating a presensitized plate, wherein after exposure is performed on the presensitized plate according to claim 12, development is performed with a developer substantially containing no alkali metal silicates and containing saccharides.

18. (canceled).

- **19. (original):** A method of treating a presensitized plate, wherein after exposure is performed on the presensitized plate according to claim 14, development is performed with a developer substantially containing no alkali metal silicates and containing saccharides.
- **20. (original):** A method of treating a presensitized plate, wherein after exposure is performed on the presensitized plate according to claim 15, development is performed with a developer substantially containing no alkali metal silicates and containing saccharides.

21. (canceled).